PTL2106

-20V/-6A P-Channel Enhancement Mode MOSFET
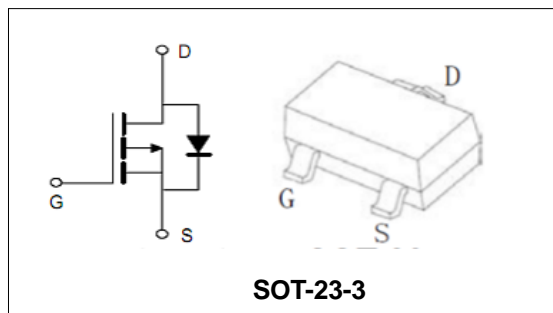
Features
- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance

BVDSS	-20	V
ID	-6	A
RDSON@VGS=-4.5V	17	mΩ
RDSON@VGS=-2.5V	20	mΩ

Applications
- Low Side Load Switch
- Battery Switch
- Optimized for Power Management Applications for Portable Products, such as Aeromodelling, Power bank, Brushless motor, Main board , and Others

SOT-23-3

Order Information

Product	Package	Marking	Reel Size	Reel	Carton
PTL2106	SOT-23-3	2106	7inch	3000PCS	180000PCS

Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (TC=25°C Unless Otherwise Noted)				
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage		-20	V
V_{GS}	Gate-Source Voltage		±12	V
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	°C
I_S	Diode Continuous Forward Current	TA =25°C	-6	A
Mounted on Large Heat Sink				
I_{DM}	Pulse Drain Current Tested (Sillicon Limit)　(Note1)	TA =25°C	-24	A
I_D	Continuous Drain current	TA =25°C	-6	A
P_D	Maximum Power Dissipation	TA =25°C	1.4	W
$R_{\theta JA}$	Thermal Resistance Junction−to−Ambient　(Note2)		89.2	°C/W

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Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)						
$V_{(BR)DSS}$	Drain- Source Breakdown Voltage	VGS=0V ID=-250µA	-20	--	--	V
I_{DSS}	Zero Gate Voltage Drain current	VDS=-20V,VGS=0V	--	--	-1	µA
I_{GSS}	Gate-Body Leakage Current	VGS=±12V,VDS=0V	--	--	±100	nA
$V_{GS(TH)}$	Gate Threshold Voltage	VDS=VGS,ID=-250µA	-0.4	--	-1.2	V
$R_{DS(ON)}$	Drain-Source On-State Resistance (Note3)	VGS=-4.5V, ID=-5.5A	--	17	25	mΩ
		VGS=-2.5V, ID=-4A	--	20	35	mΩ
Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated) (Note4)						
C_{iss}	Input Capacitance	VDS= -10V,	--	1100	--	pF
C_{oss}	Output Capacitance	VGS=0V,	--	175	--	pF
C_{rss}	Reverse Transfer Capacitance	F=1MHz	--	108	--	pF
Q_g	Total Gate Charge	VDS= -10V,	--	10	--	nC
Q_{gs}	Gate-Source Charge	ID= -6A,	--	3	--	nC
Q_{gd}	Gate-Drain Charge	VGS= -4.5V	--	4	--	nC
Switching Characteristics (Note4)						
$t_{d(on)}$	Turn-on Delay Time	VDD=-10V,	--	15	--	nS
t_r	Turn-on Rise Time	ID=-1A,	--	30	--	nS
$t_{d(off)}$	Turn-off Delay Time	RG=6Ω,	--	48	--	nS
t_f	Turn-off Fall Time	VGS=-4.5V	--	23	--	nS
Source- Drain Diode Characteristics@ TJ = 25°C (unless otherwise stated)						
V_{SD}	Forward on voltage (Note3)	IS=-2.5A,VGS=0V	--	--	-1.2	V

Note:

1.   Repetitive Rating: Pulse width limited by maximum junction temperature.

2.   Surface Mounted on FR4 Board, t ≤ 10 sec

3.   Pulse Test: pulse width ≤ 300 us, duty cycle ≤ 2%.

4.   Guaranteed by design, not subject to production testing.

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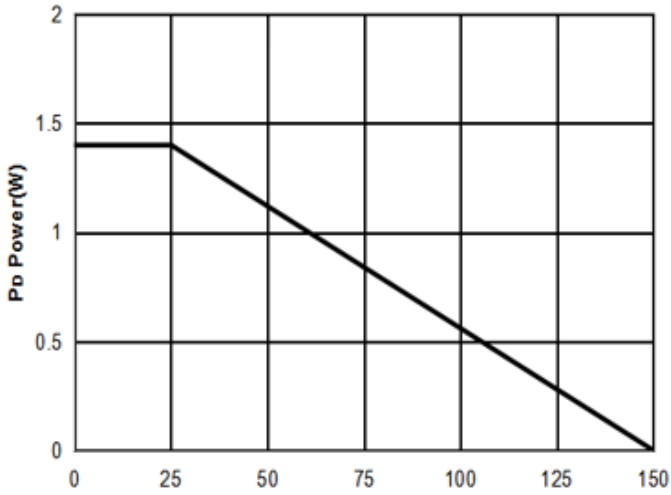
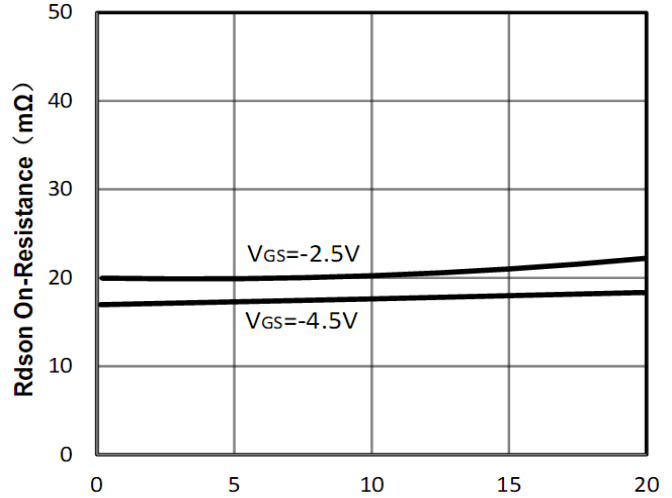## Typical Characteristics

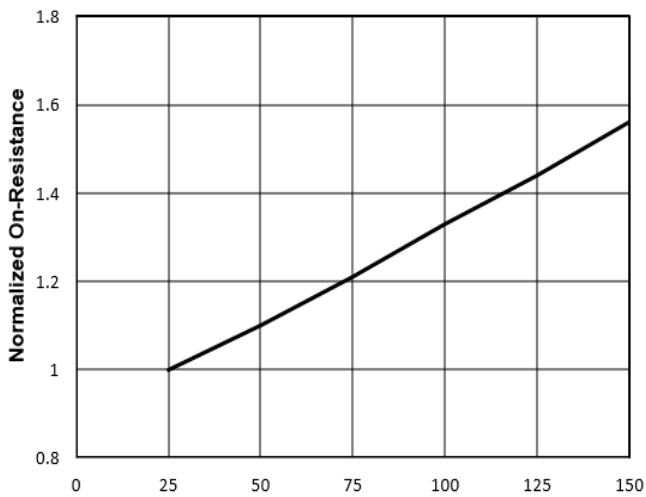Figure1：TJ Junction Temperature（°C）

Figure2：-ID Drain Current（A）

Figure3：TJ Junction Temperature（°C）
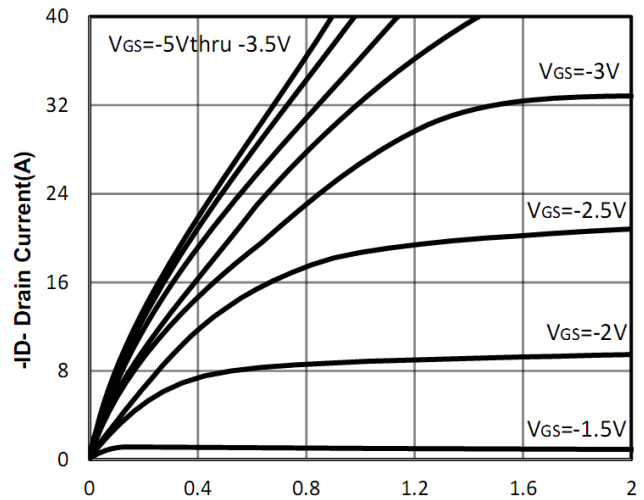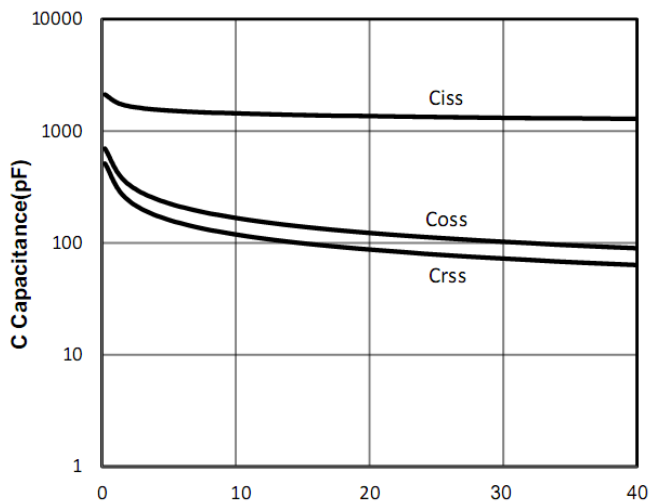
Figure4：-VDS Drain-Source Voltage（V）
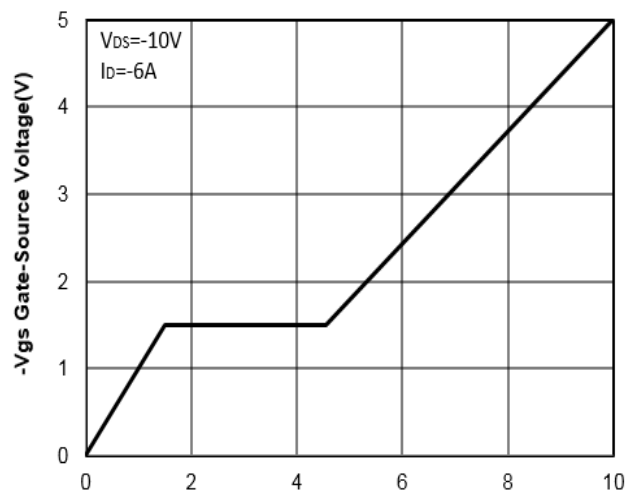
Figure5：-VDS Draun-Source Voltage（V）

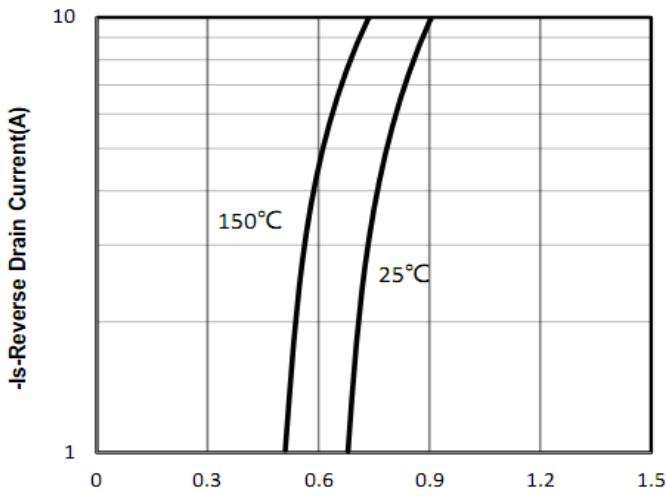Figure6：Qg Gate Charge（nC）

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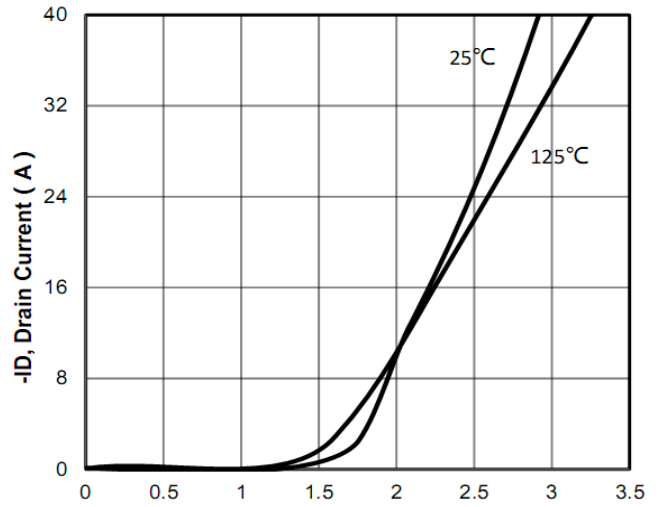

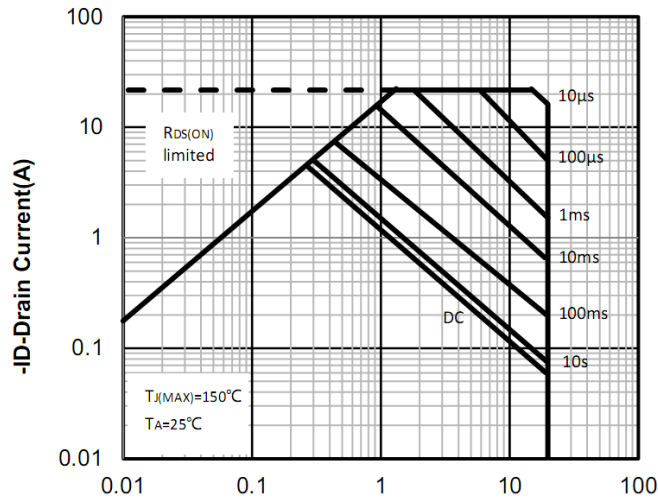Figure7：-Vsd Source-Drain Voltage（V）

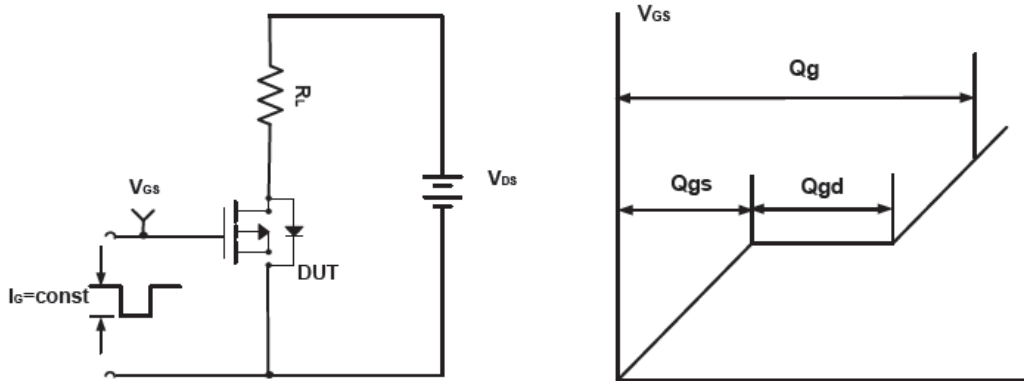Figure8：-Vgs Gate-Source Voltage（V）

Figure9：-Vds Drain -Source Voltage（V）
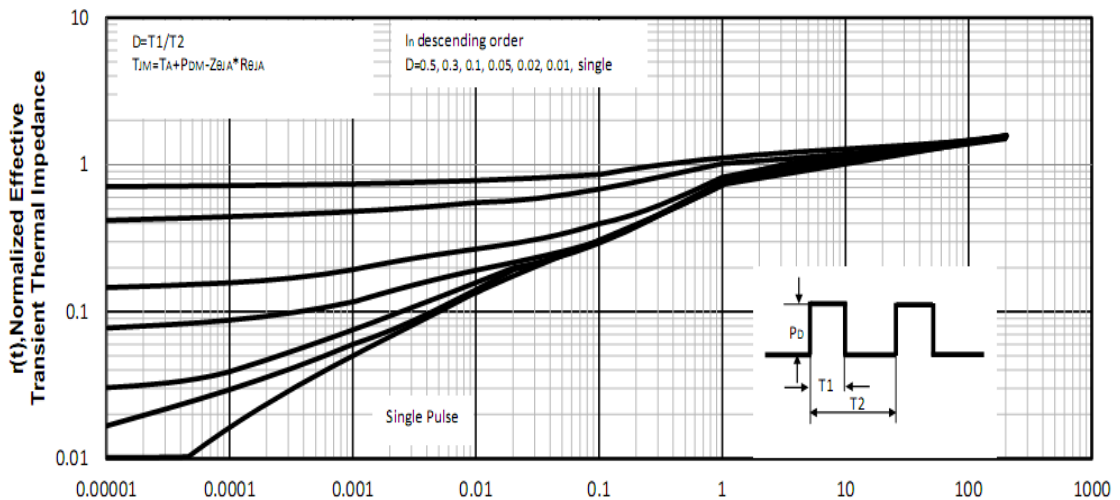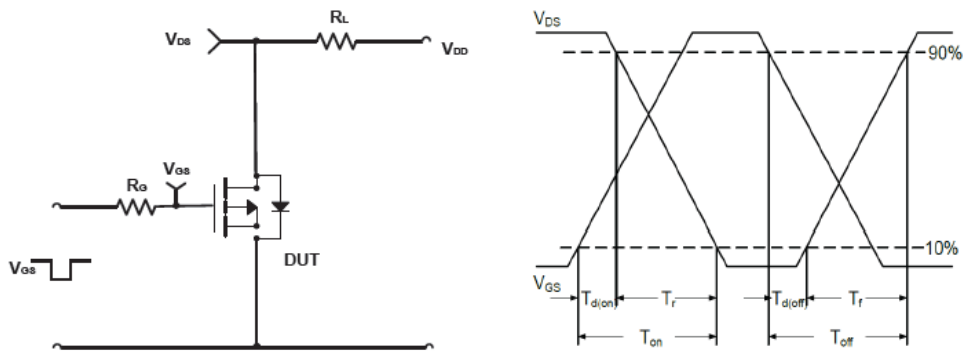

Figure10：Square Wave Pulse Duration（sec）

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Test Circuit and Waveform:

Figure A   Gate Charge Test Circuit &Waveforms

Figure B   Switching Test Circuit & Waveforms

$$EAS = \frac{1}{2} L \times I_{AS}^2$$
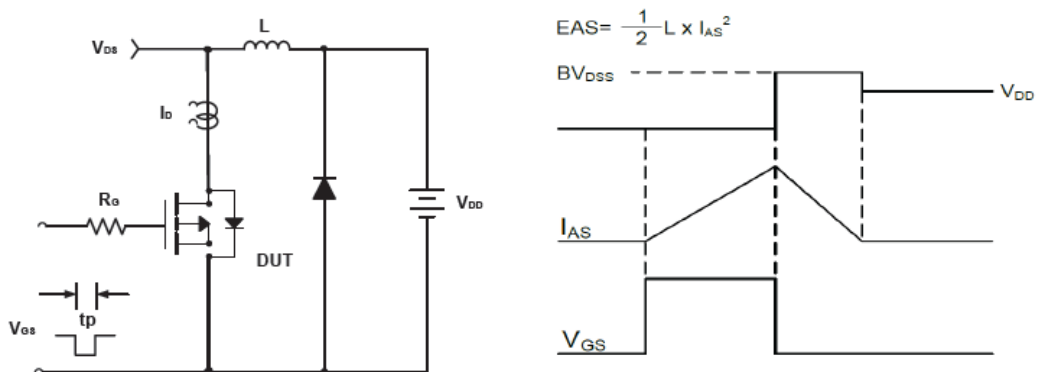
Figure C   Unclamped Inductive Switching Circuit & Waveforms

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SOT-23-3 Package Outline Dimensions (Units: mm)
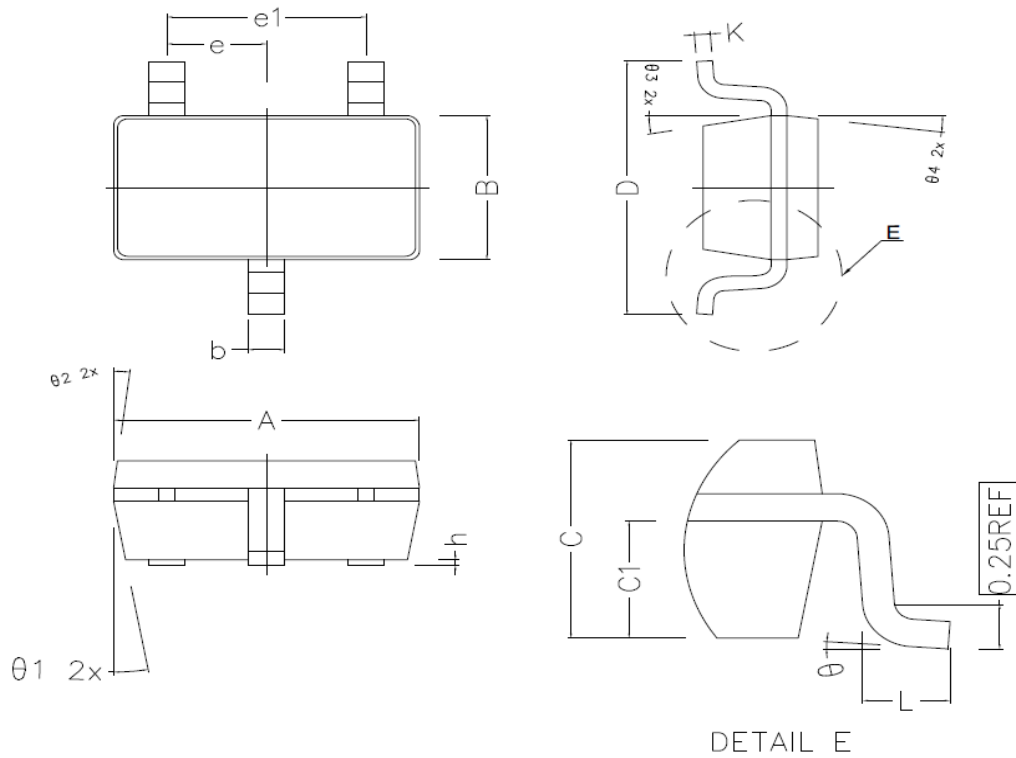
COMMON DIMENSIONS (UNITS OF MEASURE IS mm)			
	MIN	NORMAL	MAX
A	2.820	2.920	3.020
B	1.500	1.600	1.700
C	1.050	1.100	1.150
C1	0.600	0.650	0.700
D	2.650	2.800	2.950
L	0.300	0.450	0.600
b	0.280	0.350	0.420
h	0.020	0.050	0.100
K	0.120	—	0.230
e	0.950TYPE		
e1	1.900TYPE		
θ_1	10° TYPE		
θ_2	7° TYPE		
θ_3	10° TYPE		
θ_4	7° TYPE		
θ	0° ~ 8°		